

## **Modified Stanford-PKU RRAM model to simulate multilevel SET process in 1T1R arrays.**

If you have benefited from this model, please refer to the following paper and cite it:

John Reuben, Dietmar Fey and Christian Wenger, “A modeling methodology for Resistive RAM based on Stanford-PKU model with extended multilevel capability”, IEEE Transactions on Nanotechnology, 2019

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### Multilevel Modeling using Stanford RRAM model

In RRAMs, there are two ways to implement multiple states

- 1) By varying compliance current (also called multilevel SET): from the initial HRS, the RRAM is programmed to different LRS during the SET process
- 2) By varying reset voltage (also called multilevel RESET): from the initial LRS, the RRAM is programmed to different HRS during the RESET process

Since HRS variability is more compared to LRS variability in RRAM arrays, we prefer multilevel- SET process. I.e single HRS and multiple LRS. Multilevel SET is demonstrated in 1T1R arrays by IHP and other research groups.

### **SET, RESET and READ process in 1T-1R**

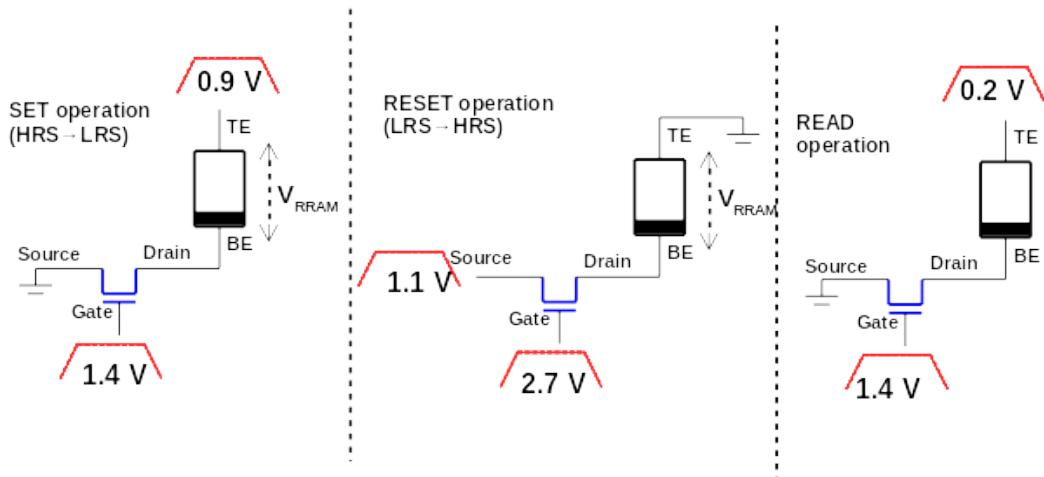


Fig.2 : Voltage pulses during SET, RESET and READ process. (The duration of SET and RESET pulses is 10  $\mu$ S )

### IHP's 1T-1R characteristics

Important observation: Read-out voltage is 0.2 V

So the characteristic of IHP's RRAM are as follows:

$$\text{HRS} = 66.66 \text{ K}\Omega \text{ (3}\mu\text{A at 0.2 V)}$$

$$\text{LRS1} = 10 \text{ K}\Omega \text{ (20}\mu\text{A at 0.2 V) when gate voltage is 1.2 V}$$

$$\text{LRS2} = 6.66 \text{ K}\Omega \text{ (30}\mu\text{A at 0.2 V) when gate voltage is 1.4 V}$$

$$\text{LRS3} = 5 \text{ K}\Omega \text{ (40}\mu\text{A at 0.2 V) when gate voltage is 1.6 V}$$

## Composite 1T1R model

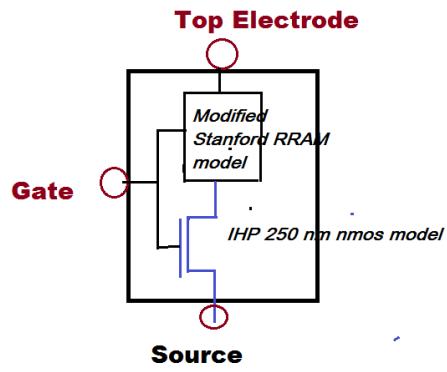


Fig. 1

## Modified Stanford RRAM model (Verilog-A code)

```

`include "constants.vams"
`include "disciplines.vams"

module Stanford_modified(TE, BE, vgate);
input vgate;
inout TE, BE;
electrical TE, BE;
electrical vgate;
// Version Parameter
parameter real version = 1.00 from(0:inf);
// Switch to select Standard Model (0) or Dynamic Model (1)
parameter integer model_switch = 0 from[0:1];

// The following constants have been pre-defined in the constants.vams
// Boltzmann's constant in joules/kelvin, 'parameter real kb = 1.3806503e-23'
parameter real kb = 1.3806503e-23;
// charge of electron in coulombs, 'parameter real q = 1.6e-19'
parameter real q = 1.6e-19;
// average switching fitting parameters g0, V0, I0, beta, gamma0
parameter real g0 = 0.25e-9 from(0:2e-9);
parameter real V0 = 0.25 from(0:10);
parameter real Vel0 = 10 from(0:1000);
parameter real I0 = 1000e-6 ;// from(0:1e-2);
parameter real beta = 0.8 from(0:inf);
parameter real gamma0 = 16 from(0:inf);
// threshold temperature for significant random variations
parameter real T_crit = 450 from(390:460);
// variations fitting parameters
parameter real deltaGap0 = 0.02 from[0:0.1];

parameter real T_smth = 500 from(400:600); // activation energy for vacancy generation
parameter real Ea = 0.6 from(0:2);
// atom spacing, a0
parameter real a0 = 0.25e-9 from(0:inf);

```

```

// initial room temperature in devices
parameter real T_ini = 273 + 25 from(0:inf);
// minimum field requirement to enhance gap formation, F_min
parameter real F_min = 1.4e9 from(0:3e9);
// For IHP's transistor, W/L = 1140/240 which is 4.75
parameter real W_by_L = 4.75;
// initial gap distance, gap_ini
parameter real gap_ini = 2e-10 from(0:100e-10);
// minimum gap distance, gap_min
// This is the main modification:g_min is a function of gate voltage and W/L of transistor
real gap_min;
// maximum gap distance, gap_max

```

```

parameter real gap_max = 19e-10 from(0:100e-10);
// thermal resistance
parameter real Rth = 1.5e3 from(0:inf);
// oxide thickness, thickness
parameter real tox = 12e-9 from(0:100e-9);
// initial random seed
parameter integer rand_seed_ini = 0 from(-1.6e9:1.6e9);
// time step boundary
parameter real time_step = 3e-9 from(1e-15:1);
// voltage V(TE, BE), Vtb; current I(TE, BE), Itb
real Vtb, Itb;
// Voltage at Gate of transistor;
real Vg;
// present temperature in devices, temp
real T_cur;
// gap time derivative, gap_ddt; random gap time derivative, gap_random_ddt
real gap_ddt, gap_random_ddt;
// present gap status
real gap;
// local enhancement factor, gamma
real gamma;
real gamma_ini;
// random number
integer rand_seed;
real deltaGap;

```

```

parameter real pulse_width = 20n;
analog begin
// bound time step
$bound_step(time_step);
// present Vtb, Itb, and local device temperature calculation, T_cur
Vtb = V(TE,BE);
Itb = I(TE,BE);
Vg = V(vgate);
T_cur = T_ini + abs(Vtb * Itb * Rth);
// calculate g_min
gap_min = (2.6e-10 * (W_by_L / Vg)) + 1.21e-10;//previously 2.6e-10.... + 1.21e-10
// $display("voltage across RRAM is = %e",Vtb);
// gap_min = (2.6e-10 * (W_by_L / (Vg-0.9+((Vtb/0.3)/sqrt((1+pow((Vtb/0.3),2))))))) + 1.21e-10;
// $display("Value of gap_min = %e ",gap_min);
// initialize random seed, rand_seed
@(initial_step)
rand_seed = rand_seed_ini;
// calculate local enhancement factor, reference RRAM_CompactModel_I.pdf
// added
gamma_ini = gamma0;

```

```

//added
    if(Vtb < 0) begin
        gamma_ini = 16;
    end
    gamma = gamma_ini - beta * pow((( gap )/1e-9), 3);

    if ((gamma * abs( Vtb )/ tox) < F_min) begin
        gamma = 0;
    end

// calculate next time step gap situation
// gap time derivative - determinant part
gap_ddt = - Vel0 * exp(- q * Ea / kb / T_cur) * sinh(gamma * a0 / tox * q * Vtb / kb / T_cur);
// gap time derivative - variation part
deltaGap = deltaGap0 * model_switch;
gap_random_ddt = $rdist_normal(rand_seed, 0, 1) * deltaGap / (1 + exp((T_crit - T_cur)/T_smth));
gap = idt(gap_ddt+gap_random_ddt, gap_ini);
// if(gap<gap_min) begin
//     gap = gap_min;
// end else if( ( gap>gap_max) begin
//     gap=gap_max;
// end
if( ( gap>gap_max) begin
    gap=gap_max;
end
Itb = I0 * exp(-gap/g0)*sinh(Vtb/V0);
I(TE,BE) <= Itb;
end
endmodule

```

### Characteristics of IHP's 1T1R

HRS= 66.66 K $\Omega$  (3 $\mu$ A at 0.2 V)

LRS1= 10 K $\Omega$  (20 $\mu$ A at 0.2 V) when gate voltage is 1.2 V

LRS2 = 6.66 K $\Omega$  (30 $\mu$ A at 0.2 V) when gate voltage is 1.4 V

LRS3= 5 K $\Omega$  (40 $\mu$ A at 0.2 V) when gate voltage is 1.6 V

### Parameters of modified Stanford RRAM model

Ea=0.6	I0=8.54e-4	Rth=1500	model_switch=1	g0=0.346e-9	V0=0.26	Vel0=0.05
Beta=0.4	gamma0=19.5	T_crit=450	DeltaGap0=0.005	T_smth=500	a0=2.5e-10	Tini=298
F_min=1.4e9	gap_ini=18.8e-10		gap_max=18.8e-10	tox=6e-9	Time_step=1e-9	

NMOS model parameters:

$t_{ox}$  = 10 nm, W = 1.14 m, L = 0.24 m,  $V_t$  (threshold voltage of MOSFET)= 0.6 V

### Simulation Steps:

1. Create a RRAM model by instantiating “Modified Stanford RRAM model” verilog-A code
2. Create nmos transistor by instantiating “nmos” from SGB25\_dev (IHP’s 250 nm CMOS library files must be installed already in the Cadence Virtuoso environment)
3. Create composite 1T1R model as shown in Fig.1
4. Set gap\_ini= 18.8e-10 and simulate SET process with voltage pulses as illustrated in Fig.2. Sample wave forms of the multilevel SET process is plotted in Figure below
5. Set gap\_ini= 18.8e-10 and simulate SET process followed by RESET to verify if the RRAM returns to the same HRS of 3  $\mu$ A in each case.

